



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-09
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGWT60H65DFB	TDTY*EWF7T5S	A	Z4LA	2015-10-09
Amount		UoM	Unit type	ST ECOPACK Grade
5380.00		mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	15.75 - 20.15 - 5.15	3	Through-hole	
Comment	Package: TO3P-3L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TDY*EWF7155					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	17.326	mg	supplier	die	Silicon (Si)	7440-21-3		13.207	mg	762251	2455
				supplier	metallization	Aluminium (Al)	7429-90-5		3.261	mg	188225	606
				supplier	Passivation	Silicon Oxide	7631-86-9		0.277	mg	15988	51
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.014	mg	808	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	693	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.175	mg	10101	33
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.009	mg	519	2
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.049	mg	2828	9
				supplier	polymer die coating	Durimide	proprietary		0.322	mg	18586	60
Lead-frame	Other inorganic materials	3405.804	mg	supplier	Alloy	Copper (Cu)	7440-50-8		3387.753	mg	994700	629694
				supplier	Alloy	Iron (Fe)	7439-89-6		3.406	mg	1000	633
				supplier	Alloy	Phosphorus (P)	12185-10-3		13.623	mg	4000	2532
				supplier	Alloy	Nickel (Ni)	7440-02-0		1.022	mg	300	190
Soft solder	Solder	54.035	mg	supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	50.523	mg	934999	9391
				supplier	solder	Tin (Sn)	7440-31-5		2.702	mg	50002	502
				supplier	solder	Silver (Ag)	7440-22-4		0.810	mg	14999	151
Bonding wire	Other inorganic materials	5.454	mg	supplier	wire	Aluminium (Al)	7429-90-5		5.454	mg	1000000	1014
Encapsulation	Other inorganic materials	1883.367	mg	supplier	mold compound	Silica vitreous	60676-86-0		1469.025	mg	779999	273053
				supplier	mold compound	Bisphenol F type epoxy resin	9003-36-5		178.921	mg	95000	33257
				supplier	mold compound	Phenol resin	9003-35-4		169.503	mg	90000	31506
				supplier	mold compound	Antimony Trioxide	1309-64-4		32.017	mg	17000	5951
				supplier	mold compound	Brominated flame retardant	Proprietary		28.251	mg	15000	5251
				supplier	mold compound	Carbon Black	1333-86-4		5.650	mg	3000	1050
Connections coating	Solder	14.014	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		14.014	mg	1000000	2605